

IN THE CLAIMS

Claims 1 to 18 and 23 to 32 are pending in this application. Please amend the claims, as follows:

1. (Currently Amended) A ~~foamed~~ resin laminate sound insulation board which is a laminated plate, comprising: at least ~~an unfoamed formable~~ a foamable resin [[to be]] foamed at a foaming temperature by heating; and a shape-formable hard plate on which the foamable resin is adhered prior to heating.
2. (Currently Amended) A ~~foamed~~ resin laminate sound insulation board which is a laminated plate, comprising: at least ~~an unfoamed~~ a first foamable resin [[to be]] foamed at a first foaming temperature by heating, ~~an unfoamed~~ a second foamable resin [[to be]] foamed at a second foaming temperature by heating, and a shape-formable hard plate, wherein the first foamable resin is adhered to the hard plate and the second foamable resin is adhered to the first foamable resin.
3. (Currently Amended) The ~~foamed~~ resin laminate sound insulation board according to claim 2, wherein the first foaming temperature of the first foamable resin is ~~differed~~ different from ~~that~~ the second foaming temperature of the second foamable resin.
4. (Currently Amended) The ~~foamed~~ resin laminate sound insulation board according to claim 2, wherein the melting point of the first formable resin is ~~differed~~ different from that of the second foamable resin.
5. (Currently Amended) The ~~foamed~~ resin laminate sound insulation board according to claim 1, ~~wherein the laminated plate is formed by laminating~~ further comprising: a non-foamable material ~~not foamable by heating,~~ laminated on said foamable resin, and said foamable resin laminated on the hard plate in this order.
6. (Currently Amended) The ~~foamed~~ resin laminate sound insulation board according to claim 5, wherein the non-foamable material is a non-foamable resin not foamable by heating.

7. (Currently Amended) The ~~foamed~~ resin laminate sound insulation board according to claim 1 ~~wherein the laminated plate is formed by laminating, further comprising: a non-foamable resin, wherein~~ said foamable resin~~[[,]]~~ is laminated on the non-foamable resin ~~not foamable by heating, and the non-foamable resin is laminated on~~ the hard plate ~~in this order.~~
8. (Currently Amended) The ~~foamed~~ resin laminate sound insulation board according to claim 1, wherein said foamable resin is heated at a temperature lower than the foaming temperature, and thermally fused to the hard plate to form the laminated plate.
9. (Currently Amended) The ~~foamed~~ resin laminate sound insulation board according to claim 6, wherein said non-foamable resin is heated at a temperature lower than said foaming temperature, and thermally fused to the foamable resin to form the laminated plate.
10. (Currently Amended) The ~~foamed~~ resin laminate sound insulation board according to claim 6, wherein ~~[[the]]~~ a melting point of said non-foamable resin is higher than ~~[[the]]~~ a melting point of said foamable resin.
11. (Currently Amended) The ~~foamed~~ resin laminate sound insulation board according to claim 6, wherein said non-foamable resin is a thermosetting resin or a thermoplastic resin.
12. (Currently Amended) The ~~foamed~~ resin laminate sound insulation board according to claim 1, wherein said foamable resin is a thermosetting resin or a thermoplastic resin.
13. (Currently Amended) The ~~foamed~~ resin laminate sound insulation board according to claim 11, wherein ~~[[the]]~~ a melting point of said thermoplastic resin is 100-260° C.
14. (Currently Amended) The ~~foamed~~ resin laminate sound insulation board according to claim 12 wherein ~~[[the]]~~ a melting point of said thermoplastic resin is 100-260° C.

15. (Currently Amended) The ~~foamed~~ resin laminate sound insulation board according to claim 1, wherein said foamable resin is formed ~~by mixing~~ from a mixture of a foaming agent that is decomposable by heating ~~[[to the]]~~ with a resin.
16. (Currently Amended) The ~~foamed~~ resin laminate sound insulation board according to claim 1, wherein said foaming temperature is set to 120-300° C.
17. (Currently Amended) A ~~foamed~~ resin laminate sound insulation board according to claim 1, wherein ~~in which~~ the foamed resin laminate sound insulation board according ~~to claim 1~~ is heated to said foaming temperature to make the foamable resin ~~[[to]]~~ into a foamed resin.
18. (Currently Amended) The ~~foamed~~ resin laminate sound insulation board according to claim 17, wherein said foamable resin is made into the foamed resin by heating after the foamed resin laminate sound insulation board is worked into a prescribed shape.
19. (Withdrawn) A method for manufacturing a foamed resin laminate sound insulation board comprising: a laminating process for laminating at least an unfoamed foamable resin to be foamed at a foaming temperature by heating and a hard plate; and a process for integrating the laminate of said foamable resin and the hard plate at a temperature lower than the foaming temperature of the foamable resin.
20. (Withdrawn) The method for manufacturing a foamed resin laminate sound insulation board according to claim 19 comprising the laminating process, said laminate integrating process, and a heating process for heating the laminate to the foaming temperature of said foamable resin to make said foamable resin to a foamed resin.
21. (Withdrawn) The method for manufacturing a foamed resin laminate sound insulation board according to claim 20 comprising said laminating process, the laminate integrating process, a molding process for working the laminate into a prescribed shape in the integrated state, and said heating process.

22. (Withdrawn) The method for manufacturing a foamed resin laminate sound insulation board according to claim 20 wherein said heating process is carried out simultaneously with a heating treatment for baking finish.
23. (Currently Amended) The ~~foamed~~ resin laminate sound insulation board according to claim 2, wherein at least one of said first and second foamable resin resins is heated at a temperature lower than the corresponding first or second foaming temperature, and thermally fused ~~to form the laminated plate to the hard plate or first foamable resin,~~ respectively.
24. (Currently Amended) The ~~foamed~~ resin laminate sound insulation board according to claim 7, wherein said non-foamable resin is heated at a temperature lower than said foaming temperature, and thermally fused ~~to form the laminated~~ to the hard plate.
25. (Currently Amended) The ~~foamed~~ resin laminate sound insulation board according to claim 7, wherein the melting point of said non-foamable resin is higher than the melting point of said foamable resin.
26. (Currently Amended) The ~~foamed~~ resin laminate sound insulation board according to claim 7, wherein said non-foamable resin is a thermosetting resin or a thermoplastic resin.
27. (Currently Amended) The ~~foamed~~ resin laminate sound insulation board according to claim 2, wherein said foamable resin is a thermosetting resin or a thermoplastic resin.
28. (Currently Amended) The ~~foamed~~ resin laminate sound insulation board according to claim 26, wherein [[the]] a melting point of said thermoplastic resin is 100-260° C.
29. (Currently Amended) The ~~foamed~~ resin laminate sound insulation board according to claim 27, wherein [[the]] a melting point of said thermoplastic resin is 100-260° C.

30. (Currently Amended) The ~~foamed~~ resin laminate sound insulation board according to claim 2, wherein said foamable resin is formed ~~by mixing~~ from a mixture of a foaming agent that is decomposable by heating ~~[[to the]]~~ with a resin.
31. (Currently Amended) The ~~foamed~~ resin laminate sound insulation board according to claim 2, wherein said foaming temperature is set to 120-300° C.
32. (Currently Amended) A ~~foamed~~ resin laminate sound insulation board according to claim 2, wherein ~~in which~~ the foamed resin laminate sound insulation board ~~according to claim 2~~ is heated to said foaming temperature to make the foamable resin ~~[[to]]~~ into a foamed resin.